Exhibit 9 – Internal Photographs

Motorola Customer Premise Equipment (CPE)

FCC ID: MIJZEPCPE-USB-01

Model No. LT 20M-00

9.0 Photographs

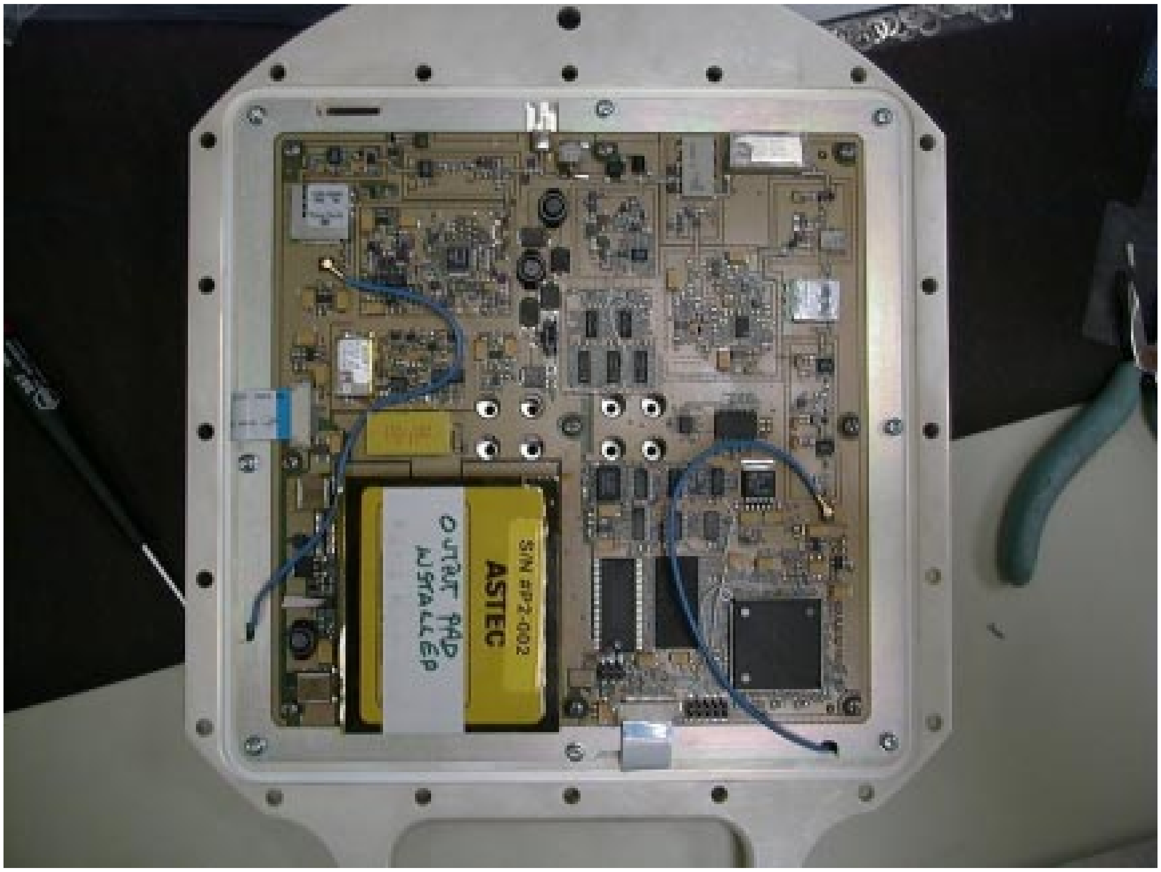

Figure 9.0-1 The Translator Assembly components are soldered/attached to a multi-layer printed circuit board that is installed into the chassis on top of the Millimeter Wave and Micro-Wave covers.

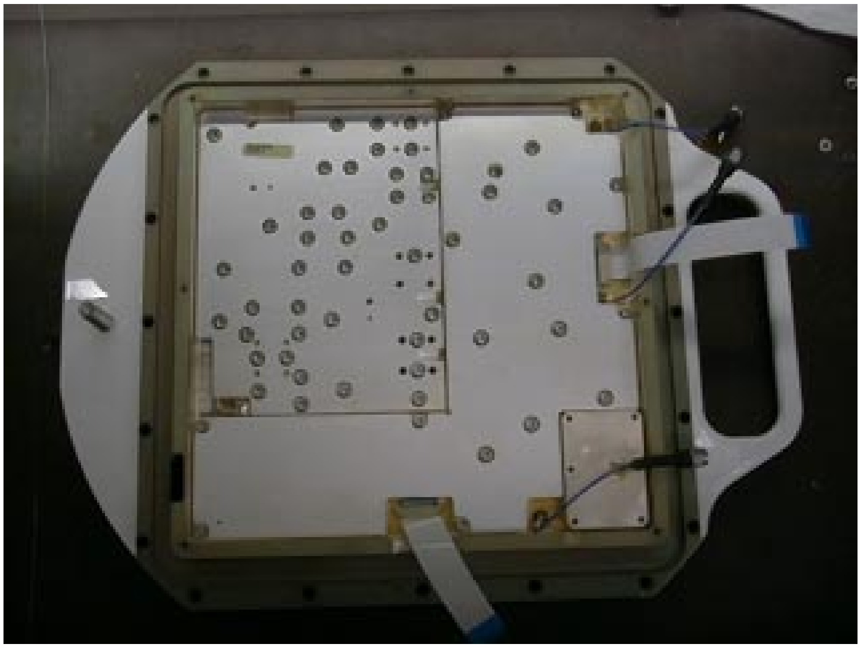

Figure 9.0-2   Housing with the Translator Printed Wiring Board Assembly removed, showing the cover plates installed over the Millimeter Wave and Microwave Assemblies.

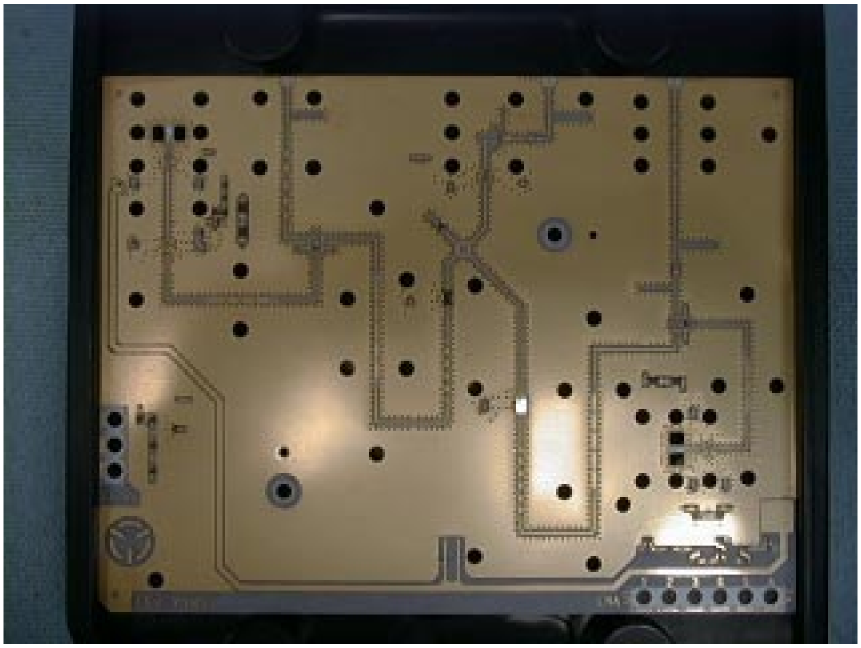

Figure 9.0-3   Millimeter Wave Assembly components are primarily MMICS (Monolithic Microwave Integrated Circuits) that are wire-bonded to a 4-layer RF micro-strip circuit board. In this view, the MMICS are almost indistinguishable.

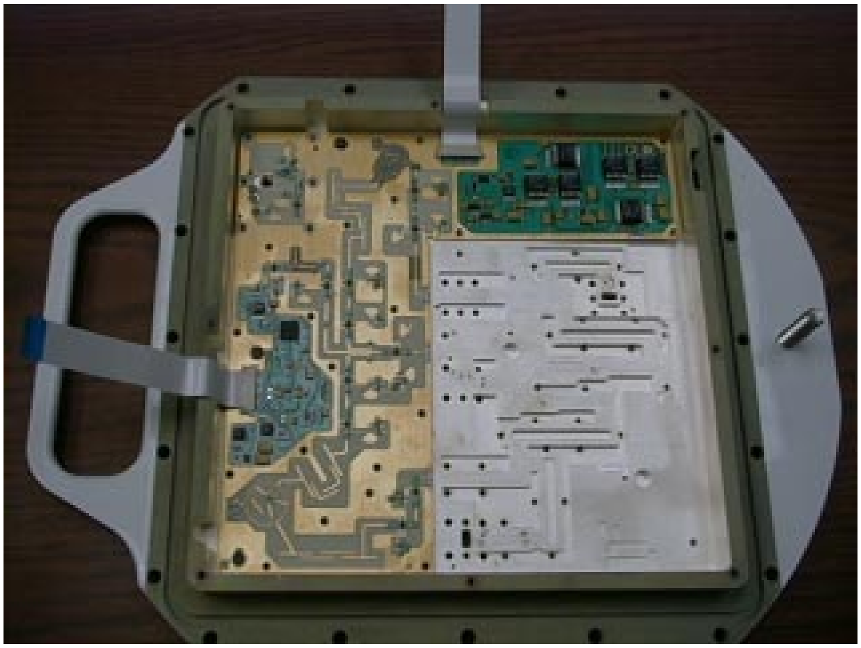

Figure 9.0-4 The Microwave assembly components are assembled onto a L-shaped 4-layer RF micro-strip circuit board to provide low-loss impedance matching inter-connections for the signal flow paths. The exposed rectangular shaped portion of the chassis shows relief channels for RF paths and components for the Millimeter Wave Assembly not yet installed.

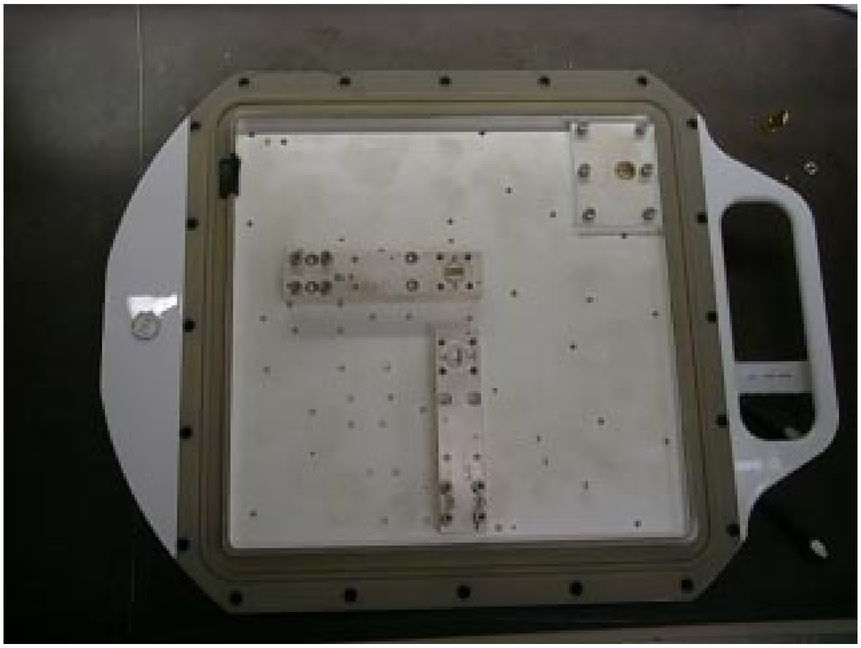

Figure 9.0-5 This view shows the wave-guide filters on the opposite side of the Millimeter/Microwave chassis.